



MMSZ5221B - MMSZ5259B

500mW SURFACE MOUNT ZENER DIODE

Features

- 500mW Power Dissipation
- General Purpose, Medium Current
- Ideally Suited for Automated Assembly Processes
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOD123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Weight: 0.01 grams (approximate)



Top View

Ordering Information (Note 3)

Part Number	Case	Packaging
(Type Number)-7-F*	SOD123	3000/Tape & Reel

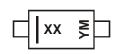
*Add "-7-F" to the appropriate type number in Electrical Characteristics Table. Example: 6.2V Zener = MMSZ5234B-7-F.

Notes: 1. No purposefully added lead. Halogen and Antimony Free.

2. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.

3. For packaging details, go to our website at http://www.diodes.com.

Marking Information



xx = Product Type Marking Code (See Electrical Characteristics Table) YM = Date Code Marking Y = Year (ex: N = 2002) M = Month (ex: 9 = September)

Date Code Key

	Jan		гер	IVIA		Apr	IVIA	v	Jun	Jul		Aug	Sep		Oct			Dec
Month	lan		Feb	Ма		A	May		lum	1		A	Sam		Oct	Nov		Dee
Code	J	K	L	М	Ν	Р	R	S	Т	U	V	W	Х	Y	Z	Α	В	С
Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015



Maximum Ratings @T_A = 25°C unless otherwise specified

Chara	cteristic	Symbol	Value	Unit
Forward Voltage	@ I _F = 10mA	V _F	0.9	V

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4) @T _L = 75°C	PD	500	mW
Thermal Resistance, Junction to Ambient Air (Note 4)	R ₀ JA	350	°C/W
Thermal Resistance, Junction to Lead (Note 5)	R _{eJL}	150	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Maximum Zener Test Maximum Reverse Zener Voltage Range (Note 6) Impedance Current Leakage Current (Note 6) f = 1KHz Туре Туре Number Code Zzĸ @ Izĸ Z_{ZT} @ I_{ZT} Vz @ Izt IZT @ V_R IR = 0.25mA Max (V) Min (V) ٧ Nom (V) mΑ Ω μA MMSZ5221B C1 2.4 2.52 20 1200 100 1.0 2.28 30 MMSZ5223B 2.7 C3 2.57 2.84 20 30 1300 75 1.0 MMSZ5225B C5 3.0 2.85 3.15 20 30 1600 50 1.0 MMSZ5226B G1 3.3 3.14 3.47 20 28 1600 25 1.0 MMSZ5227B G2 3.6 3.42 3.78 20 24 1700 15 1.0 MMSZ5228B G3 3.9 20 23 1900 10 1.0 3.71 4.10 MMSZ5229B G4 4.3 4.09 4.52 20 22 2000 5.0 1.0 MMSZ5230B G5 4.7 4.47 4.94 20 19 1900 5.0 2.0 MMSZ5231B E1 17 2.0 5.1 4.85 5.36 20 1600 5.0 MMSZ5232B E2 5.6 5.32 5.88 20 11 1600 5.0 3.0 MMSZ5233B E3 6.0 5.70 6.30 20 7 1600 5.0 3.5 MMSZ5234B E4 5.89 7 1000 6.2 6.51 20 5.0 4.0 MMSZ5235B E5 6.46 20 5 750 6.8 7.14 3.0 5.0 MMSZ5236B F1 7.5 7.13 7.88 20 6 500 3.0 6.0 MMSZ5237B F2 7.79 20 8.2 8.61 8 500 3.0 6.5 MMSZ5238B F3 8.7 8.27 9.14 20 8 600 3.0 6.5 MMSZ5239B F4 9.1 8.65 9.56 20 10 600 3.0 7.0 MMSZ5240B F5 10 9.50 10.50 20 17 3.0 8.0 600 MMSZ5241B H1 11 10.45 11.55 20 22 600 2.0 8.4 MMSZ5242B H2 12 11.40 12.60 20 30 600 1.0 9.1 MMSZ5243B 12.35 9.5 13 H3 13 13.65 0.5 9.9 600 MMSZ5245B 14.25 H5 15 15.75 8.5 16 600 0.1 11 MMSZ5246B J1 16 15.20 16.80 7.8 17 600 0.1 12 MMSZ5248B 17.10 18.90 21 J3 18 7.0 600 0.1 14 MMSZ5250B J5 20 19.00 21.00 6.2 25 600 0.1 15 MMSZ5251B K1 22 20.90 23.10 5.6 29 600 0.1 17 MMSZ5252B K2 24 25.20 33 22.80 5.2 18 600 0.1 MMSZ5254B K4 27 25.65 28.35 5.0 41 600 0.1 21 MMSZ5255B K5 28 26.60 29.40 4.5 44 600 0.1 21 MMSZ5256B 49 M1 30 28.50 31.50 4.2 23 600 0.1 MMSZ5257B M2 33 31.35 34.65 3.8 58 700 0.1 25 MMSZ5258B M3 36 37.80 3.4 70 700 0.1 27 34.20 MMSZ5259B M4 39 37.05 40.95 3.2 80 800 0.1 30

Electrical Characteristics @T_A = 25°C unless otherwise specified

Notes:

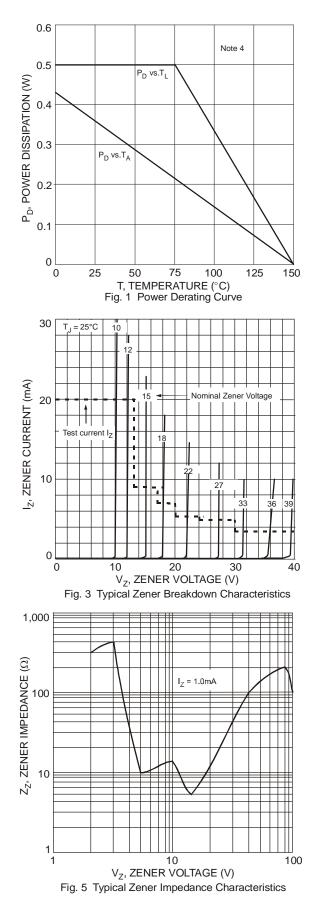
4. Device mounted on FR-4 substrate, single-sided, PC boards, with minimum recommended pad layout.

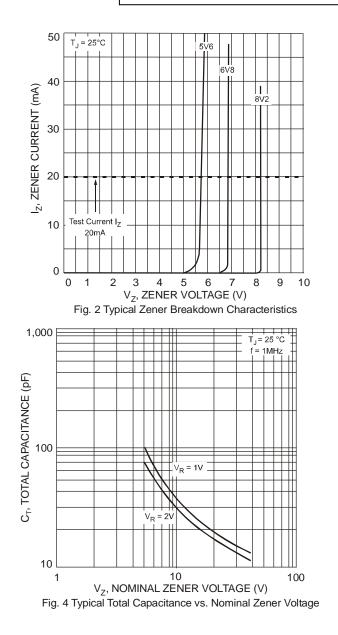
5. Thermal Resistance measurement obtained via infrared scan method.

6. Short duration pulse test used to minimize self-heating effect.



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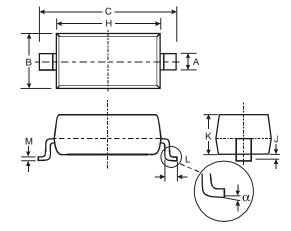


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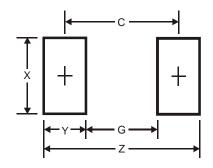


Package Outline Dimensions



SOD123						
Dim	Min Max					
Α	0.55 Typ					
В	1.40	1.70				
C	3.55	3.85				
H	2.55	2.85				
J	0.00 0.10					
ĸ	1.00 1.35					
L	0.25	0.40				
М	0.10	0.15				
α	0	8°				
All Dir	nensions	s in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
Z	4.9
G	2.5
Х	0.7
Y	1.2
C	3.7

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